AMENDMENTS TO THE SPECIFICATION

Please amend the Title to read as follows:

REVERSE OPTICAL MASTERING FOR DATA STORAGE DISK~~S~~ STAMPER

Applicants request that on page 1, after the Title and before the Technical Field, the following paragraph be inserted:

This application is a continuation of U.S. Application Number 09/850,252, filed May 7, 2001, which is a divisional application of U.S. Application Number 09/730,246, filed December 5, 2000, which is a continuation-in-part (CIP) of U.S. Application Number 09/055,825, filed April 6, 1998, now abandoned. The entire content of each of the aforementioned applications is incorporated herein by reference.

Applicants also request that the paragraph on page 1, lines ~~27-23~~ 23-26 be amended to read as follows: SB 8-13-09

Conventional mastering typically utilizes laser light with wavelength, λ, in a range of 350 nm $< \lambda <$ 460 nm focused through an objective with a numerical aperature (NA) of 0.75 $<$ NA $<$ 0.90 to give a theoretical ~~g~~Gaussian spot size of:

~~SS = 0.57 λ NA (full width at half maximum intensity (FWHM)).~~

SS = 0.57 λ / NA (full width at half maximum intensity (FWHM)).

Please amend the paragraph on page 18, line 27 to page 19, line 12 to read as follows:

In one preferred embodiment, a master disk made using the master disk recording process in accordance with the present invention is utilized in a second generation disk molding process. Suitable disk molding processes including one suitable second generation disk molding process capable of making multiple optical disk stampers from one master disk is as disclosed in U.S. Patent 6,365,329 ~~Application Serial No. _____, filed _____ titled "PROCESS FOR MAKING MULTIPLE DATA STORAGE DISK STAMPERS FROM ONE MASTER"(Kerfeld) (Attorney Docket No. I201.106.101), filed the same date as the instant application~~, the disclosure of which is incorporated herein by reference. The above-referenced patent ~~application~~ utilizes a unique disk molding process which includes a photopolymerization step which is non-destructive